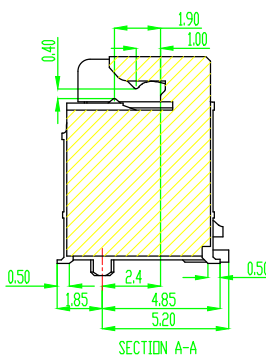
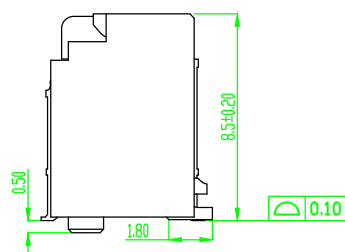
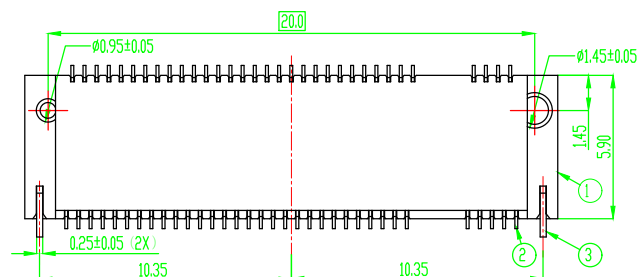
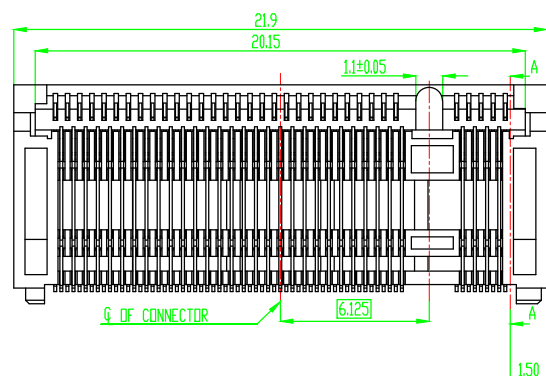
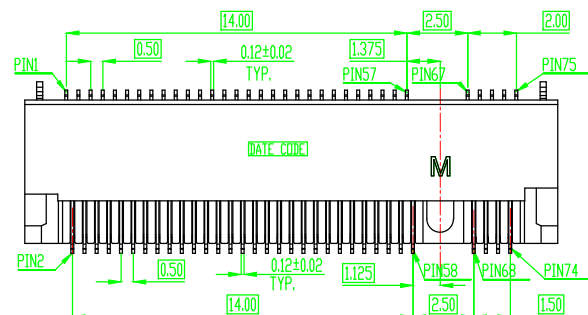
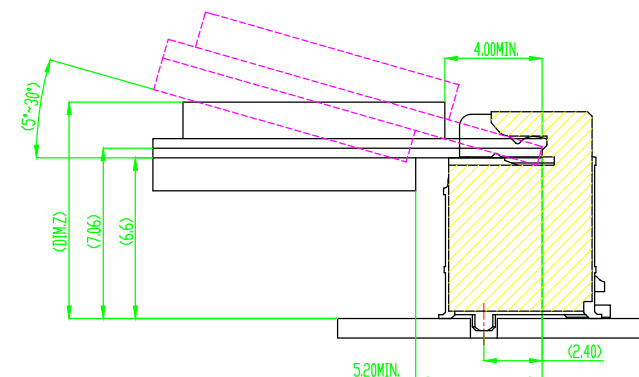


C-DWG



REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
03	--	Optimize housing structure	2020.06.22	DAWEI
04	--	Update the Typesetting	2021.10.16	BOB

- NOTES:
- ELECTRICAL CHARACTERISTICS:
 - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
 - VOLTAGE RATING: 50V AC.
 - INSULATION RESISTANCE: 500 MEGOHMS MIN. AT 500V DC.
 - DIELECTRIC WITHSTANDING VOLTAGE: 300V AC RMS AT 60Hz, FOR 1 MINUTE.
 - CONTACT RESISTANCE: 55 MILLIOHMS MAX. PER PIN INITIAL.
R=20 MILLIOHMS MAX. PER PIN AFTER FULL ENVIRONMENT TESTING.
 - MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.
 - OPERATION TEMPERATURE: -40°C TO +80°C.
 - RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260°C, 10~20S.
 - RECOMMEND THE ANGLE THAT INTENT IS MINIMIZE INSERTION/EXTRACTION FORCE.



6. PART NO. 12HN-F03B-A825*R
NGFF TYPE 03LCP B-BLACK
R REEL GG/F 10u" 55u" A10u" B15u" C30u"
FLOWING WATER CODE

DIM. MAX(mm)	MODULE TYPE
8.85	S1&D1
9.00	S2&D2
9.15	S3&D3&D4&D5
9.40	S4
9.65	S5

3	METAL TAB	STAINLESS STEEL (SUS)	2	10u" NICKEL UNDER PLATING 100u" MATTIE TIN PLATING OVER ALL
2	CONTACT	PHOSPHOR BRONZE (C5210)	67	50u" NICKEL UNDER PLATING GOLD FLASH PLATING AT TAIL AREA GOLD FLASH OR 5u" GOLD PLATING OR 10u" GOLD PLATING OR 15u" GOLD PLATING OR 30u" GOLD PLATING AT CONTACT AREA
1	HOUSING	LCP	1	UL94V-0, HALOGEN FREE, BLACK COLOR
ITEM	DESCRIPTION	MATERIAL	Q'TY	TREATMENT

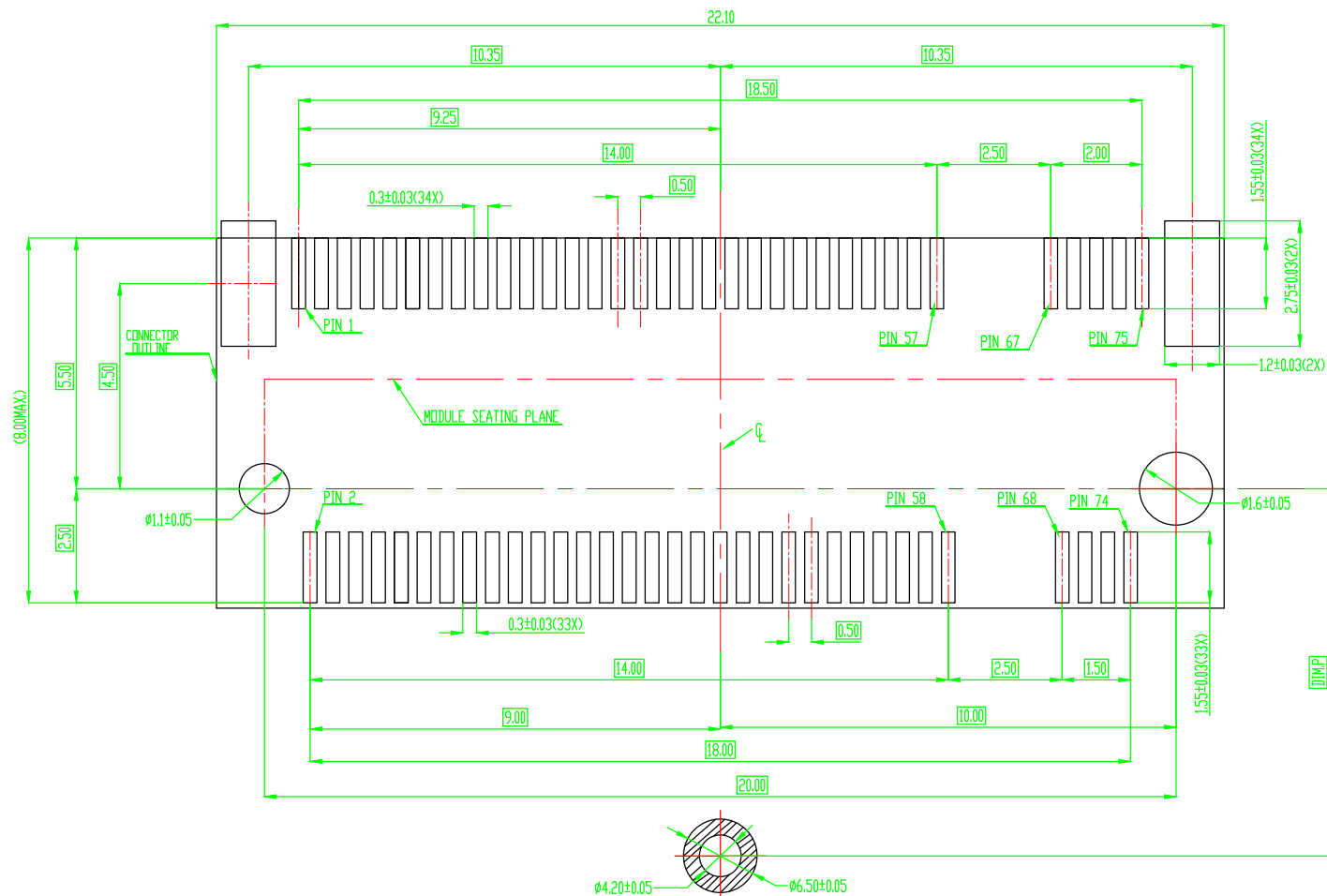
DIM	TOL	DIM	DEG
X	±0.50	X°	±8°
X.X	±0.35	X.X°	±5°
X.XX	±0.25	X.XX°	±3°
X.XXX	±0.15	X.XXX°	±2°

JOINSOO建舜電子

DESIGN:	BOB	2021.10.16	DRAW NO.	DRAW NAME:	
CHECK:			P/N: 12HN-F03B-A825*R	M.2(NGFF)CONNECTOR H=8.5MM	
APPROVED			UNIT: mm	SCALE: 1:1	MODEL:
			REV: 04	SHEET: 1/4	

C-DWG

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
03	--	Optimize housing structure	2020.06.22	DAWEI
04	--	Update the Typesetting	2021.10.16	BOB



DATUM Z IS THE PCB SOLDER SURFACE

DIM	TOL	DIM	DEG
X	±0.50	X°	±8°
X.X	±0.35	X.X°	±5°
X.XX	±0.25	X.XX°	±3°
X.XXX	±0.15	X.XXX°	±2°
DESIGN:	BOB	2021.10.16	
CHECK:			
APPROVED			

JOINSOO建舜電子

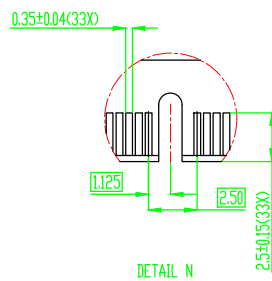
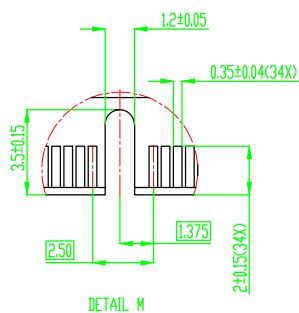
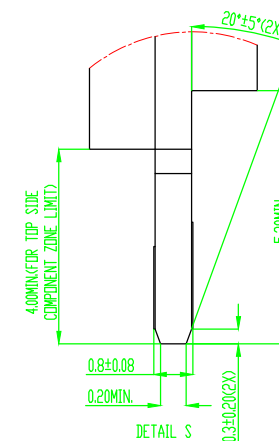
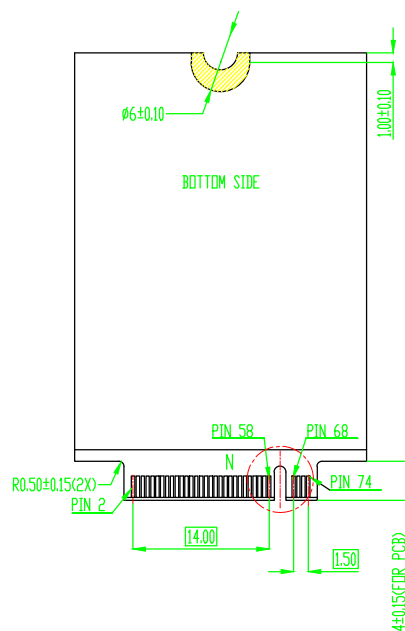
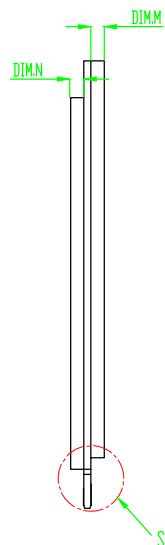
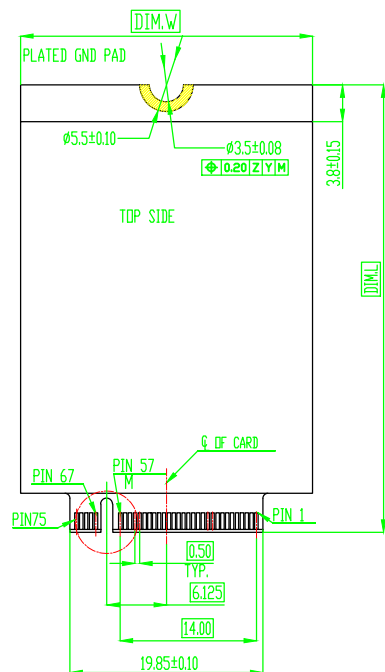
FILE:	DRAW NAME:
DRAW NO.	M.2(NGFF)CONNECTOR H=8.5MM
P/N: 12HN-F03B-A825*R	
UNIT: mm	SCALE: 1:1
REV: 04	SHEET: 2/4
MODEL:	



CI0701A-1 6

C-DWG

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
03	--	Optimize housing structure	2020.06.22	DAWEI
04	--	Update the Typesetting	2021.10.16	BOB



TYPE XX	XX - XX - X	KEY ID
LENGTH(mm)	20	
	42	
DIML	60	
	80	
	110	
WIDTH(mm)	22	
DIMW	30	

COMPONENT MAX HEIGHT(mm)		
	DIMN	DIMM
S1	1.2	0
S2	1.35	0
S3	1.5	0
S4	1.75	0
S5	2.0	0
D1	1.2	1.35
D2	1.35	1.35
D3	1.5	1.35
D4	1.5	0.7
D5	1.5	1.5

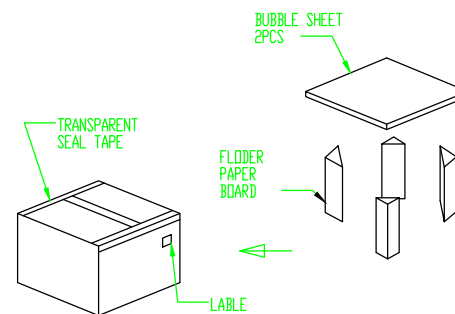
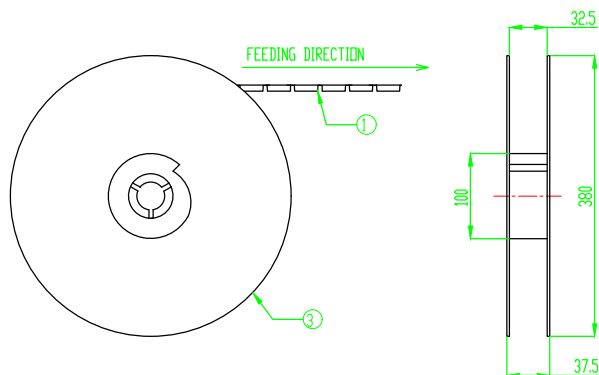
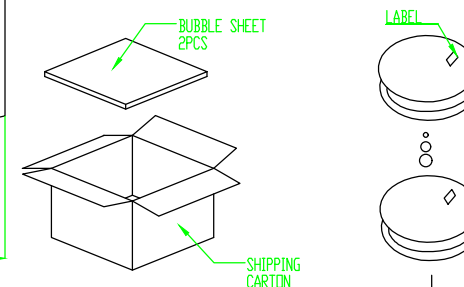
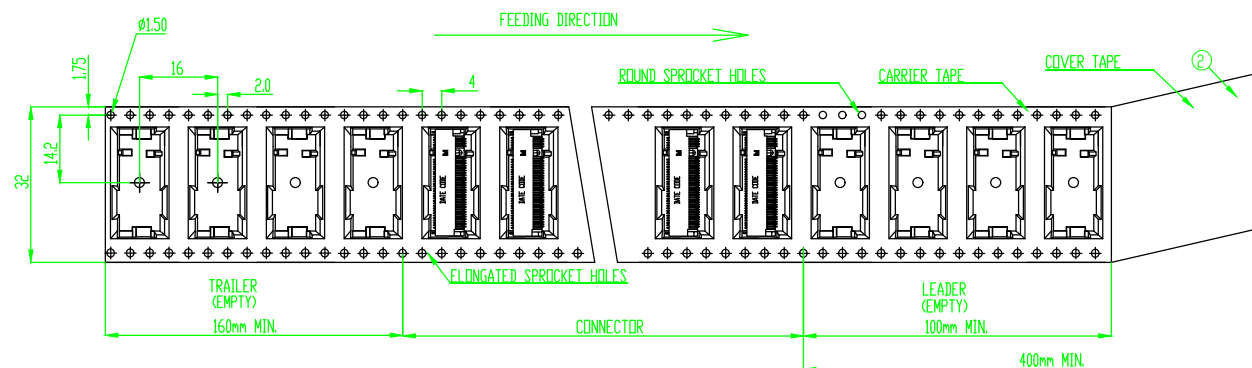
DIM	TOL	DIM	DEG
X	±0.50	X°	±8°
X.X	±0.35	X.X°	±5°
X.XX	±0.25	X.XX°	±3°
X.XXX	±0.15	X.XXX°	±2°
DESIGN:	HL.W	2021.10.16	
CHECK:			
APPROVED			

JOINSOO建舜電子

FILE:	DRAW NAME:
DRAW NO.	M.2(NGFF)CONNECTOR H=8.5MM
P/N: 12HN-F03B-A825*R	
UNIT: mm	SCALE: 1:1
REV: 04	SHEET: 3/4
MODEL:	BOB

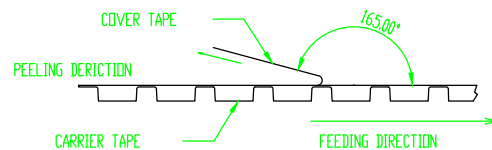
C-DWG

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
03	--	Optimize housing structure	2020.06.22	DAWEI
04	--	Update the Typesetting	2021.10.16	BOB



NOTES:

- COVER TAPE PEELING STRENGTH : 0.01 kgf MIN & 0.13 kgf MAX. AT 300mm/min.
- 10 POKETS HOLE PITCH CUMULATIVE TOLERANCE $\pm 0.20\text{mm}$.



3	REEL	POLYSTYRENE
2	COVER TAPE	POLYESTER
1	CARRIER TAPE	POLYSTYRENE
ITEM	DESCRIPTION	MATERIAL

DIM	TOL	DIM	DEG
X	± 0.50	X°	$\pm 8^\circ$
X.X	± 0.35	X.X°	$\pm 5^\circ$
X.XX	± 0.25	X.XX°	$\pm 3^\circ$
X.XXX	± 0.15	X.XXX°	$\pm 2^\circ$

DESIGN:	BOB	2021.10.16
CHECK:		
APPROVED		

JOINSOO建舜電子

FILE:	DRAW NAME:
DRAW NO.	M.2(NGFF)CONNECTOR H=8.5M
P/N: 12HN-F03B-A825*R	
UNIT: mm	SCALE: 1:1
REV: 04	SHEET: 4/4